

Electronic Version v18
Stylesheet Version v18.0

Title of Invention

HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR SUBSTRATE

HARMANA KANTAN KANTA

Application Number:

09/912844

Confirmation Number:

5915

First Named Applicant:

Thomas Haverstock

Attorney Docket Number:

Search string:

(6521466 or 6541278 or 6546946 or 6550484

or 6558475 or 6561213 or 6561220 or 6561481

or 6561767 or 6564826 or 5217043 or

20020001929).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Remarks

Note: Remarks are not for responding to an office action.

Non US Patent and Publication references shall be filed under a separate paper transmittal. The current electronic filing contains part 4 out of a total of 4 electronic filings. Fee has been paid in previous electronic filing.

Examiner Name	Date
Rann Karkar	11-26-03

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Attorney Docket Number:

Search string:

(5900107 or 5904737 or 5932100 or 5934991 or 5981399 or 5989342 or 6005226 or 6017820 or 6029371 or 6037277 or 6053348 or 6056008 or 6077053 or 6082150 or 6085935 or 6097015 or 6128830 or 6145519 or 6159295 or 6164297 or 6203582 or 6216364 or 6239038 or 6241825 or 6251250 or 6277753 or 6286231 or 6305677 or 6334266 or 6344174 or 6388317 or 6389677 or 6418956 or 6436824 or 6454945 or

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Remarks

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Examiner Name	Date
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FORM PTO-1449 (Modified)

(37 CFR § 1.98(b))

U.S. Department of Commerce Patent and Trademark Office

Attorney Docket No.: SSI-00501

Applicants: Maximilian A. Biberger et al.

Serial No.: 09/912,844

INFORMATION DISCLOSURE STATEMENT BY APPLICANT
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Filing Date: July 24, 2001

Group Art Unit: 1763

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Sheet 2 of 2 FORM PTO-1449 (Modified) U.S. Department of Commerce Patent and Trademark Office Attorney Docket No.: SSI-00501 Serial No.: 09/912,844 INFORMATION DISCLOSIFIE STATEMENT BY APPLICANT MADE STATEMENT BY APPLICANT Sheets If Necessary) Applicants: Maximilian A. Biberger et al. Filing Date: July 24, 2001 Group Art Unit: 1763 (37.CFR & 1.98(b)) FOREIGN PATENTS OR PUBLISHED FOREIGN PATENT APPLICATIONS Translation Document Number **Publication Date** Country / Patent Office Class Subclass Yes No BJ BK BL ВМ BN BO OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication) BP Hideaki Itakura et al., "Multi-Chamber Dry Etching System", Solid State Technology, April 1982, pp. 209-214. Sun, Y.P. et al., "Preparation of Polymer-Protected Semiconductor Nanoparticles Through the Rapid Expansion of Supercritical Fluid Solution," Chemical Physics Letters, pp. 585-588, May 22, 1998. BQ Dahmen, N. et al., "Supercritical Fluid Extraction of Grinding and Metal Cutting Waste Contaminated with Oils," Supercritical Fluids - Extraction and Pollution Prevention, ACS Symposium Series, Vol. 670, pp. 270-279, 21 Oct 1997. BR Xu, C. et al., "Submicron-Sized Spherical Yttrium Oxide Based Phosphors Prepared by Supercritical CO2-Assisted aerosolization and pyrolysis," Appl. Phys. Lett., Vol. 71, No.12, September 22, 1997, pp. 1643-1645. BS Courtecuisse, V.G. et al., "Kinetics of the Titanium Isopropoxide Decomposition in Supercritical Isopropyl Alcohol," Ind. Eng. Chem. Res., Vol. 35, No. 8, pp. 2539-2545, Aug 1996. вт Gallagher-Wetmore, P. et al., "Supercritical Fluid Processing: A New Dry Technique for Photoresist Developing," SPIE Vol. 2438, pp.694-708, Jun. 1995. BU ΒV Purtell, R, et al., "Precision Parts Cleaning using Supercritical Fluids," J. Vac, Sci, Technol. A. Vol. 11, No. 4, July 1993, pp. 1696-1701. Matson, D.W. et al., "Rapid Expansion of Supercritical Fluid Solutions: Solute Formation of Powders, Thin Films, and Fibers," Ind. Eng. Chem. Res., Vol. 26, No. 11, pp. 2298-2306, 1987. BW Tolley, W.K. et al., "Stripping Organics from Metal and Mineral Surfaces using Supercritical Fluids," Separation Science and Technology, Vol. 22, pp. 1087-1101, 1987. ВX BY Joseph L. Foszcz, "Diaphragm Pumps Eliminate Seal Problems", Plant Engineering, pp. 1-5, February 1, 1996. ΒZ Bob Agnew, "WILDEN Air-Operated Diaphragm Pumps", Process & Industrial Training Technologies, Inc., 1996. CA CB CC CD CE CF CG CH CI CJ

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> HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR Title of Invention SUBSTRATE

09/912844 Application Number: Confirmation Number: 5915

09/912844

First Named Applicant:

Attorney Docket Number:

(2617719 or 2625886 or 3744660 or 3968885 or 4029517 or Search string: 4091643 or 4245154 or 4341592 or 4355937 or 4367140 or

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> HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR Title of Invention SUBSTRATE

Application Number: 09/912844 Confirmation Number: 5915

09/912844

First Named Applicant: Maximilian Biberger

Astorney Docket Number:

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Electronic Version v18 Stylesheet Version v18.0

> HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR Title of SUBSTRATE invention

Application Number: Confirmation Number: 5915

09/912844

First Named Applicant: Maximilian Biberger

Attorney Docket Number.

Search string:

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Title of

HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR

SUBSTRATE

Application Number: 09/912844

09/912844

Confirmation Number: \$915

First Named Applicant: Thomas Haverstock

Attorney Docket Number:

Search string:

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